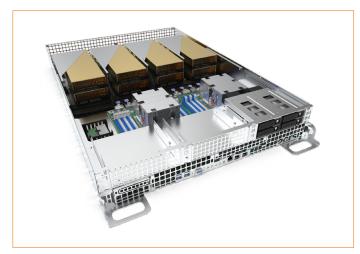




# OCtoPus 1.8SR

### OCP READY IMMERSION COOLING SERVER 2 OpenU / 8 GPUs





No contractua

## Key Features per node



21-inch 20penU



**Dual socket E (LGA 4677)** 5th and 4th Gen Intel® Xeon® Scalable



32x DDR5 @ 4800MHz



8x PCIe 5.0 x16 for GPUs 1x PCle 5.0 x8, HH-HL 1x PCIe 5.0 x16, HH-HL



Immersion cooling



SCAN THE CODE! TO DISCOVER MORE ABOUT THIS PRODUCT

#### 5th Gen Intel® Xeon® Processors

The latest Intel® Xeon® Scalable Processors are designed for the demand of high scalability, high density computing, and widest range of workloads. With up to 64 cores these processors are built to handle the most intensive data center workloads, from Data Analytics and IoT/Edge applications

to HPC and AI workloads.

Intel® Xeon® 5th Gen processors feature advanced security technologies to help protect data in an ever-changing threat landscape, while opening up new

business opportunities.
With Intel® AMX, Intel® SSE4.2, Intel® AVX, Intel® AVX2 and Intel® AVX-512 enabled, the Godi 1.8SR-NV8-G is the only system giving access to the full range of HPC and Al applications on any deployements.

#### **Immersion cooling ready**

The OCtoPus 1.8SR is specifically designed for immersion cooling configurations, offering unrivalled efficiency in heat dissipation. The immersion cooling process involves immersing server components in a dielectric liquid, ensuring more efficient heat transfer compared to traditional air cooling methods. The Atlantis 1GG capitalises on this principle, using immersion cooling to achieve precise temperature control and significantly reduce the power consumption associated with thermal management.

#### **Incredible GPUs Density**

With cutting-edge immersion cooling technology, the OCtoPus1.8SR server allows you to power up to 8 high-performance GPUs in a compact 2U chassis—without any power constraints. Each GPU can deliver its full potential at up to 350W, ensuring your workloads run faster and more efficiently, all while staying cool and reliable. Say goodbye to overheating limits and hello to ultimate performance.

#### OCP-inspired power distribution: streamlined and reliable

Adopt OCP principles with our bar-type power distribution, offering scalable

Simplify infrastructure by reducing complexity, minimizing cable clutter and improving overall system reliability.

Guarantee consistent performance with a standardized power supply, reducing complexity.

cing the risk of breakdowns and downtime.





# **OCtoPus 1.8SR**



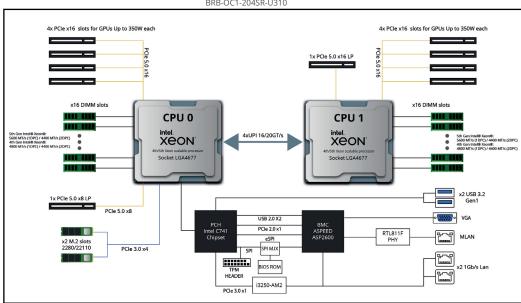
#### **SKU based on options**

This product is available with different options.
This table provides valuable information about the features and capabilities associated with each SKU (stock keeping unit), enabling potential customers and internal stakeholders to make informed decisions. Each SKU has been carefully classified according to the options available, providing a clear picture of the functionality associated with each variant.

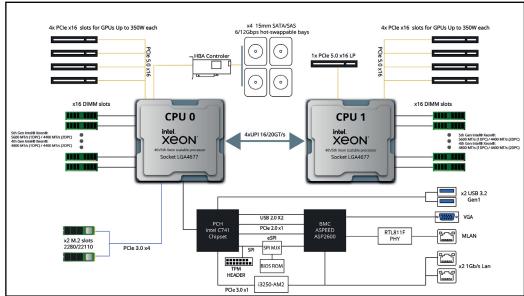
SKU	4xSata/SAS cage	Spec
BRB-OC1-208SR-U310	No	8x PCle 5.0 x16 for Dual slot GPUs cards (Front) 2x PCle 5.0 x16 for HH-HL cards (Front) 2x M.2 NVMe PCie 5.0 x2 2280/22110 (internal) 1x OCP3.0 PCle 5.0x16 (front)
BRB-OC1-208SR-U311	Yes	8x PCle 5.0 x16 for Dual slot GPUs cards (Front) 1x PCle 5.0 x16 for HH-HL cards (Front) 2x M.2 NVMe PCie 5.0 x2 2280/22110 (internal) 4x 15 mm Sata/SAS hot-swappable bays

## **BLOCS DIAGRAMS**

BRB-OC1-204SR-U310



BRB-OC1-204SR-U311







# **OCtoPus 1.8SR**

# **SPECIFICIATIONS**

system	Model	OCtoPus 1.8SR	
	Form factor	21-inch 2OpenU	
	Dimension	880 x 537 x 43mm (D x W x H)	
	Cooling technology	Immersion Cooling One phase	
Storage	Internal type per node	1x M.2 (Gen3 x4 link, PCle or SATA 6Gb/s); Form factor: 22110/2280 [CPU0] 1x M.2 (Gen3 x4 link, PCle or SATA 6Gb/s); Form factor: 22110/2280 [CPU1]	
	External type per node	4x 15mm SATA/SAS 6/12Gbps hot-swappable bays (Optional)	
	RAID controler	MegaRAID 9660-16i (Gen4) Tri-Mode RAID Adapter (Optional)	
Motherboard	CPU per node	Dual socket E (LGA 4677) 5th and 4th Gen Intel® Xeon® Scalable TDP up to 350W	
	Chipset	System on chip	
	Expansion slots per node	4x PCIe x16 (Gen5 x16 link), FH-FL DW [CPU0]* 4x PCIe x16 (Gen5 x16 link), FH-FL DW [CPU1] * *For GPU TDP up to 350W, NVL2 supported 1x PCIe x8 (Gen5 x8 link), HH-HL [CPU0] 1x PCIe x16 (Gen5 x16 link), HH-HL [CPU1]	
	TPM per node	1x TPM header with SPI interface for TPM 2.0 module optional	
	вмс	Aspeed 2600	
Memory	Total slots per node	16+16 DIMM slots (2DPC)	
	Total Capacity per node	RDIMM modules up to 96GB supported 3DS RDIMM modules up to 256GB supported	
	Memory type	DDR5 up to 5600MHz (5th gen), 4800MHz (4th gen)	
Network	Onboard	1x Realtek RTL8211E for dedicated management GLAN 2x 1GbE LAN ports (1 x Intel® i350-AM2), support NCSI	
1/0	Front	4x USB 3.2 Gen1 type A 1x DB15 (VGA) 2x RJ45 1x RJ45 Management port	
	Switch / LED	1x Power button with LED 1x ID button with LED 1x HDD LED 1x Status LED 1x System reset button	
Management	Software	Aspeed® AST2600 management controller	
solution	Remote management	BMC Remote control based on Aspeed® AST2600 remote ma nagement controller. (Power Control Configuration, Chassis Identify, Boot Option, iKVM, BMC Account Configuration)	
Power supply	Туре	OCP technology ORV3 48V DC	
Operating	Operating temperature	10°C ~ 35°C (50°F ~ 95°F)	
environement	Non-operating temperature	Non operation temperature: -40°C ~ 60°C (40° ~ 140°F)	
	Operative relative humidity	95%, non-condensing at 35° C	
Warranty	<b>2CRSi</b> hardware warranty includes a one year, parts and labour with return to 2CRSi selling entity. Customers may purchase an extended warranty of up to 3 years on parts and labour with different support levels. Please contact 2CRSi at <a href="mailto:support@2crsi.com">support@2crsi.com</a> or reach your sales point of contact for complete warranty details including limitations and transferability. <a href="mailto:2crsi.com/global-location">2crsi.com/global-location</a>		